

PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES

Please delete the title on the page 1, lines 1-3 and replace with:

PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES

Page 11, line 18, after "also" insert --has a microelectronic package core 150' and--.

Page 12, line 9, change "FIG. 6" to --FIG. 7--.

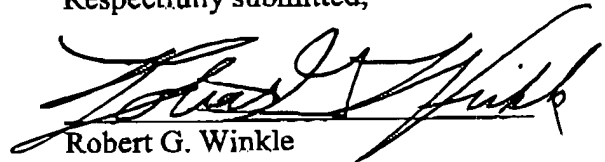
Please cancel claims 1-9, without prejudice.

REMARKS

Claims 10-33 remain in the application. The title has been amended to be more descriptive per the suggestion of the Office. The Specification has been amended to include a reference to element 150', as illustrated in FIG. 6b and 6c, and to correct an inadvertent typographical error. No new subject matter has been added.

Please forward further communications to the address of record. If the Examiner needs to contact the below-signed attorney to further the prosecution of the application, the contact number is (503) 712-1682.

Respectfully submitted,


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Dated: January 23, 2002